MEMMAP
Memory Maps

Highlights
› Multicore Microcontroller with embedded Flash
› Scratch-Pad RAM (PSPR and DSPR) closely coupled to TriCore™
› Flash memories accessible via PMU
› Up to 8 MB Flash, up to 2 MB RAM
› Contiguous Memory maps

Key Features
Compatible address maps across family

Versatile addressing modes

Customer Benefits
› Memory hierarchy allows optimal code performance & application portability
› Easy handling of cacheable and peripheral address space
MEMMAP

Compatible address maps across family

- AURIX™ TC2xx has the following memories:
  - Program and Data Flash Memory (PFlash/DFlash): Flash memory is used for information that does not change in time (e.g. the program running on the microcontroller)
  - User Configuration Blocks (UCB): This is an area in DFlash, where protection data is stored (e.g. unique chip identifier, trimming data, etc.)
  - BootROM (BROM): It is a part of the PMU and it is a read-only memory. A fixed piece of code is placed in the BootROM. The microcontroller start-up code is executed out of the BootROM and its content is not user readable (security feature)
  - Program & Data Scratch-Pad RAM (PSPR/DSPR): Allows the CPU to access code/data faster compared to the other RAMs and Flashes
  - Program & Data Cache (PCACHE/DCACHE): Cache memory is high-speed RAM. This area of the memory is used for repeatable reads and writes, where fast access to the data/code is needed
  - LMU: SRI peripheral providing access to volatile memory resources
    - LMURAM: Local memory for general purpose usage
    - TRAM: Trace RAM used for tracing
    - EMEM: Emulation and debug memory (available only in the Emulation Devices)
MEMMAP
Compatible address maps across family

- TriCore™ 4 GB addressable memory map is organized into segments of 256 MB
- A Segment is identified by the A[31:28] bits of the system address
- Each segment allows access to a specific area and it is used to define cacheable and non-cacheable areas
- This structure ensures the portability of applications across the devices of the family (considering that all needed modules are included in the device)
- A good understanding of the memory structure enables the user to optimize the code in order to achieve optimal run-time performance

<table>
<thead>
<tr>
<th>Segment</th>
<th>Memory</th>
</tr>
</thead>
<tbody>
<tr>
<td>Segments 0-7</td>
<td>Multiprocessor space (e.g. CPUs Scratch-Pad RAM)</td>
</tr>
<tr>
<td>Segment 8</td>
<td>Cached PFlash, BROM and EBU (if available)</td>
</tr>
<tr>
<td>Segment 9</td>
<td>Cached LMURAM (if available) and EMEM (if available)</td>
</tr>
<tr>
<td>Segment 10</td>
<td>Non-cached PFlash, DFlash, BROM and EBU (if available)</td>
</tr>
<tr>
<td>Segment 11</td>
<td>Non-cached LMURAM (if available) and EMEM (if available)</td>
</tr>
<tr>
<td>Segment 12-13</td>
<td>Reserved</td>
</tr>
<tr>
<td>Segment 14</td>
<td>Peripheral Space</td>
</tr>
<tr>
<td>Segment 15</td>
<td>Peripheral Space</td>
</tr>
</tbody>
</table>
MEMMAP
Versatile addressing modes

› Each CPU has access to
  – its own memory or other CPUs’ memories via its global segment (0-7)
  – its own DSPR at offset 0 via the local address (0xD000_0000)
  – its own PSPR at offset 0x0010_0000 (1MB) via the local address (0xC000_0000)

› This provides
  – the best usage of TriCore™ addressing modes for optimum code-density (single instruction access)
  – unique address for CPU Scratch-Pad RAMs in the system
MEMMAP
System integration

› Each segment of the memory is either peripheral space or cached/non-cached memory

› In the TriCore™ Architecture, different segments have different access characteristics

› Access to a segment outside the implemented memory size will result in a trap
IMPORTANT NOTICE

The information given in this document shall in no event be regarded as a guarantee of conditions or characteristics ("Beschaffenheitsgarantie").

With respect to any examples, hints or any typical values stated herein and/or any information regarding the application of the product, Infineon Technologies hereby disclaims any and all warranties and liabilities of any kind, including without limitation warranties of non-infringement of intellectual property rights of any third party.

In addition, any information given in this document is subject to customer’s compliance with its obligations stated in this document and any applicable legal requirements, norms and standards concerning customer’s products and any use of the product of Infineon Technologies in customer’s applications.

The data contained in this document is exclusively intended for technically trained staff. It is the responsibility of customer’s technical departments to evaluate the suitability of the product for the intended application and the completeness of the product information given in this document with respect to such application.

For further information on the product, technology, delivery terms and conditions and prices please contact your nearest Infineon Technologies office (www.infineon.com).

WARNINGS

Due to technical requirements products may contain dangerous substances. For information on the types in question please contact your nearest Infineon Technologies office.

Except as otherwise explicitly approved by Infineon Technologies in a written document signed by authorized representatives of Infineon Technologies, Infineon Technologies’ products may not be used in any applications where a failure of the product or any consequences of the use thereof can reasonably be expected to result in personal injury.